



Micro Modules

(Substrates with Built-in ICs, Products Utilizing with SESUB)

Bluetooth V4.0 Smart Single Mode Module

SESUB-PAN-T2541

Caution

**The products in this catalog will be or have been
stopped production**

| | |
|--------------------------|---------------|
| Discontinue Issue Date | Oct 16, 2017 |
| Last Purchase Order Date | Jan. 31, 2018 |
| Last Shipment Date | Jun. 30, 2018 |

Please refer to our Web site about replacement information.

Micro Modules

(Substrates with Built-in ICs, Products Utilizing with SESUB) Bluetooth V4.0 Smart Single Mode Module

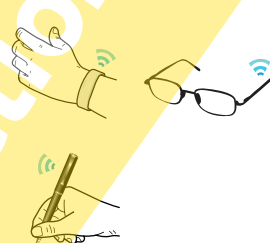
Overview of SESUB-PAN-T2541

FEATURES

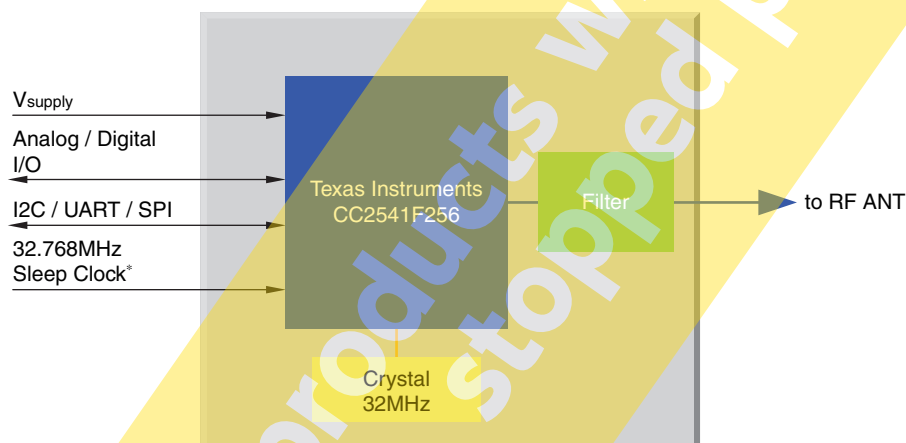
- Micro size (4.6×5.6×1.0mm) ideal for wearable devices.
- Communicable with Bluetooth® Smart Ready compatible devices.
- Separate antenna type that provides more flexibility for product design.

APPLICATION

- Health care, sports & fitness devices
(physical activity monitor, thermometer, blood pressure monitor, blood oxygen monitor, blood sugar monitor, heart rate monitor, etc.)
- Wearable computers
(bracelet type, watch type, ring type, glass type, shoe, hat, shirt, etc.)
- Home & entertainment devices
(remote control, sensor tag, toy, lighting apparatus, etc.)
- PC accessories
(mouse, keyboard, stylus pen, presentation pointer, etc.)



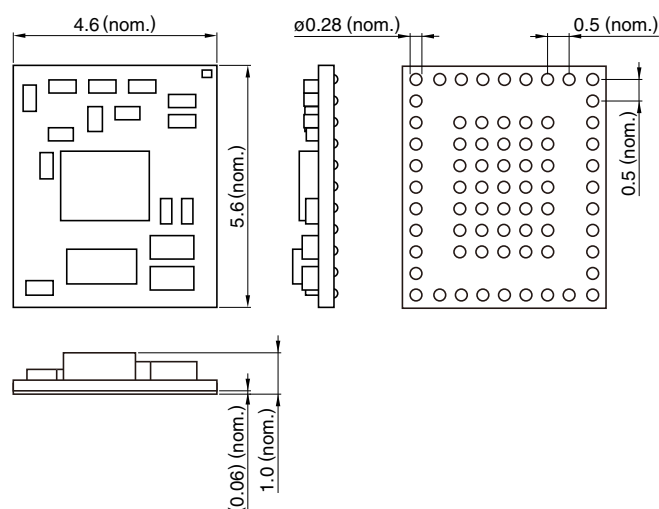
BLOCK DIAGRAM



○ Bluetooth® and Bluetooth® Low Energy are the standards established by Bluetooth Special Interest Group (SIG).

SESUB-PAN-T2541

■ SHAPE & DIMENSIONS



Dimensions in mm

■ ELECTRICAL CHARACTERISTICS

□ CHARACTERISTICS SPECIFICATION TABLE

| | |
|---------------------------------|-----------------------------------|
| Communication standards | 2.4GHz Bluetooth® V4.0 low energy |
| Wireless output power (dBm)typ. | 0 |
| Communication range (m)* | 10 |
| Interface | UART/SPI/I2C/GPIO/ADC |

* Line-of-sight distances. Depending on antenna properties.

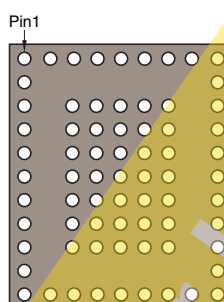
SESUB-PAN-T2541

MODULE TERMINAL

| | | | | | | | | |
|----------------|-----------|-----------|------------|------------|------------|-------------|------------|------------|
| 1 GND | 2 P2_1 | 3 P2_0 | 4 VDO | 5 VDA_1 | 6 VDA_2 | 7 GND | 8 RST_N | 9 GND |
| 36 P2_2 | | | | | | | | 10 P0_0 |
| 35 GND | | GND | GND | GND | GND | GND | | 11 P0_1 |
| 34 P2_4/32k | | GND | GND | GND | GND | GND | | 12 P0_2 |
| 33 P2_3/32k | | GND | GND | GND | GND | GND | | 13 P0_3 |
| 32 P1_7 | | GND | GND | GND | GND | GND | | 14 P0_4 |
| 31 P1_6 | | GND | GND | GND | GND | GND | | 15 P0_5 |
| 30 P1_1 | | GND | GND | GND | GND | GND | | 16 P0_6 |
| 29 P1_2 | | GND | GND | GND | GND | GND | | 17 P0_7 |
| 28 P1_3 | | | | | | | | 18 P1_0 |
| 27 GND | 26 SCL | 25 SDA | 24 P1_4 | 23 P1_5 | 22 GND | 21 2G_RF | 20 GND | 19 GND |

Module Bottom View

| | |
|-------|--|
| RF | |
| POWER | |
| Clock | |
| I/O | |
| Cont | |
| GND | |



EVALUATION BOARD

Based on the IC manufacturer-provided evaluation environment (TDK part number: SP13801)

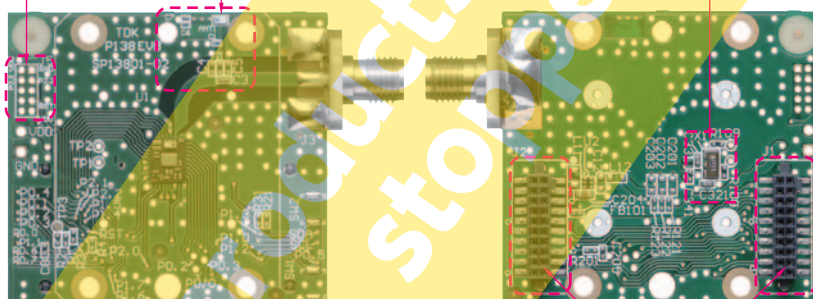
- The product is used by connecting to the IC evaluation kits of IC manufacturers.
- All software development environments and programming tools are provided by IC manufacturers.
- Various development materials of IC manufacturers are available as they are, which enables smooth development of products.
- We also offer evaluation kits which enables to evaluate product functions easily. (TDK part number: SP13808)

* For more details, please contact us.

Equipped with a program writing terminal

A chip antenna on the evaluation board

Equipped with a land pattern for a crystal unit for generating a sleep clock



Connectors to evaluation boards of the IC manufacturers